Special Issue

Heat Transfer and Its Innovative Applications

Message from the Guest Editors

Many innovative and high-end techniques have been developed and employed for changing our daily lives, namely, artificial intelligence (AI) technology, autonomous car, hyper-loop for high-speed transportation, miniaturization of electronic devices, and heat dissipation from cooling films to outer space, and so on. However, these innovative technologies can not reach their optimal performance without adequate techniques for heat transfer or a well-control of temperature during operation. Manuscripts are welcome to be submitted to cover the topics of thermal management of data centers, electronic devices, renewable energy applications, autonomous cars, thin films with well-defined structures for reflection or emission of thermal radiation, two-phase heat transfer phenomenon on surfaces with hierarchical structures, and applications of AI with regards to heat transfer. Furthermore, we invite manuscripts that focus on novel research regarding the development of components, equipment, and techniques involving thermal processes. However, special topics are not limited to the aforementioned ones.

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Editors-in-Chief

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